

Final Product/Process Change Notification

202208001F01

Issue Date: 07/08/2022

Effective Date:05/11/2022

Here is your personalized quality information concerning products our customers and partners purchased from Ampleon.

For detailed information we invite you to view this notification online

Management Summary

Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Introduction of Silver sinter die attach technology in OMP780 package Phase1

Information Notification

The soft solder die bond process is replaced by a lead free Silver sinter die bond process. For details see the presentation available in the ePCN tool. Phase 1 include non-High Aspect Ratio die sizes.

Why do we implement this change?

The Silver sinter die attach process is introduced to make products in OMP780 packages RoHS compliant, standardize the assembly process with other OMP platforms, improve void control and lower and tighten the Rth distribution.

Identification of affected Products

Top side marking

RHF code on product marking and packing labels will change from H (exempted lead and Halogen free) to D (Lead free and Halogen free)

Product availability

Sample information

Samples are available upon request

Production

Planned first shipment

07/11/2022

Impact

Improve void control to lower and tighten the Rth distribution. RHF code on product marking and packing labels will change from H (exempted lead and Halogen free) to D (Lead free and Halogen free)

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 2022-09-06.

Remarks

RHF code on product marking and packing labels will change from H (exempted lead and Halogen free) to D (Lead free and Halogen free)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact Ampleon "Quality Support Team".

For all Quality Notification content inquiries, please contact your local Ampleon Sales Support team.

At Ampleon we are dedicated to creating optimal value for our customers.

Ampleon Quality Management Team.

Customer

Partnumber	12NC
BLM9D1822S-60PBGY	934960229518
BLM9D2327S-50PBGY	934960259518
BLM9H0610S-60PGY	934960276518

